Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. (No claims are amended.)

Listing of Claims:

Claims 1-61 (Canceled)

Claim 62 (Previously presented): A socket for receiving a first electronic component, said socket comprising:

a support substrate;

a plurality of elongate, resilient first contact structures extending from a first side of said support substrate and disposed to contact said first electronic component;

a plurality of second contact structures extending from a second side of said support substrate, ones of said first contact structures electrically connected to ones of said second contact structures;

a second electronic component, wherein said second contact structures are in electrical communication with said second electronic component.

Claim 63 (Previously presented): The socket of claim 62, wherein ones of said second contact structures are joined to said second electronic component.

Claim 64 (Previously presented): The socket of claim 62, wherein ones of said second contact structures are soldered to said second electronic component.

Claim 65 (Previously presented): The socket of claim 62, wherein ones of said second contact structures comprise solder.

Claim 66 (Previously presented): The socket of claim 62, wherein said ones of said second contact structures comprise solder balls.

Claim 67 (Previously presented): The socket of claim 62, wherein said support substrate comprises electrically conductive through holes electrically connecting said ones of said first contact structures with said ones of said second contact structures.

Claim 68 (Previously presented): The socket of claim 62 further comprising a frame disposed to support said first electronic component in spaced relationship to said support substrate.

Claim 69 (Previously presented): The socket of 68, wherein said first contact structures extend a length from said first side of said support substrate, and said frame maintains a minimum distance between said first electronic component and said support substrate, wherein said length is greater than said minimum distance.

Claim 70 (Previously presented): The socket of claim 68, wherein said frame comprises a stiffener element comprising at least one opening through which at least one of said resilient contact structures extends.

Claim 71 (Previously presented): The socket of claim 70, wherein said stiffener element is disposed so as to limit wiping of said resilient contact structures on said first electronic component.

Claim 72 (Previously presented): The socket of claim 62 further comprising a sliding member configured to slidingly engage said first electronic component and said resilient contact structures.

Claim 73 (Previously presented): The socket of claim 62 further comprising a member disposed to support said first electronic component, wherein said member is moveable to move said first electronic component into engagement with said first contact structures.

Claim 74 (Previously presented): The socket of claim 62 further comprising a moveable member configured to move said resilient contact structures into engagement with said first electronic component.

Claim 75 (Previously presented): The socket of claim 62, wherein said resilient contact structures comprises wires.

Claim 76 (Previously presented): The socket of claim 75, wherein said wires comprise a coating.

Claim 77 (Previously presented): The socket of claim 76, wherein said coating comprises a material having a greater yield strength than a material of said wires.

Claim 78 (Previously presented): The socket of claim 62 further comprising a spring mechanism disposed to press said first electronic component against said first contact structures.

Claim 79 (Previously presented): The socket of claim 78, wherein said second contact structures are attached to said second electronic component.

Claim 80 (Previously presented): The socket of claim 78, wherein said second contact structures are soldered to said second electronic component.

Claim 81 (Previously presented): The socket of claim 62 further comprising means for effecting pressure connections between said first electronic component and said first contact structures.

Claim 82 (Previously presented): The socket of claim 81, wherein said second contact structures are attached to said second electronic component.

Claim 83 (Previously presented): The socket of claim 81, wherein said second contact structures are soldered to said second electronic component.

Claim 84 (Previously presented): A socket for receiving a first electronic component, said socket comprising:

a support substrate;

first connection means for forming a plurality of readily reversible, pressure-based electrical connections with a first electronic component disposed on a first side of said support substrate;

second connection means for forming a plurality of permanent electrical connections with a second electronic component disposed on a second side of said support substrate; and

means for electrically connecting said first connection means with said second connection means.

Claim 85 (Previously presented): The socket of claim 84 further comprising support means for supporting said first electronic component in spaced relationship to said support substrate.

Claim 86 (Previously presented): The socket of claim 84 further comprising means for limiting a wipe of said first connection means on said first electronic component.

Claim 87 (Previously presented): The socket of claim 84 further comprising means for slidingly engaging said first electronic component and said first connection means.

Claim 88 (Previously presented): The socket of claim 84 further comprising means for supporting said first electronic component and moving said first electronic component into engagement with said first connection means.

Claim 89 (Previously presented): The socket of claim 84 further comprising means for moving said first connection means into engagement with said first electronic component.